



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-06-01
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STL8N6LF6AG	R1Y5*7L62AC2	A	SH1A	2017-06-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	90.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	6, 5, 1	8	pin	
Comment	Package: PowerFLAT 5x6 WF			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	R1Y5*7L6ZAC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.173	mg	supplier	die	Silicon (Si)	7440-21-3		1.118	mg	953112	12422
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	11935	156
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	2558	33
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.007	mg	5968	78
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.016	mg	13640	178
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	853	11
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.009	mg	7673	100
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	851	11
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.004	mg	3410	44
				Leadframe	Copper & its alloys	43.788	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.996	mg	22746	11067
supplier	alloy	Iron Phosphide (FeP)	26508-33-8						0.06	mg	1370	667
supplier	alloy	Zinc (Zn)	7440-66-6						0.052	mg	1188	578
supplier	metallization	Nickel (Ni)	7440-02-0						0.327	mg	7468	3633
supplier	metallization	Phosphorus (P)	12185-10-3						0.002	mg	45	23
Soft solder	Solder	1.239	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.183	mg	954802	13144
				supplier	solder	Silver (Ag)	7440-22-4		0.031	mg	25020	344
				supplier	solder	Tin (Sn)	7440-31-5		0.025	mg	20178	278
Bonding wire & Ribbon	Other inorganic materials	0.531		supplier	wire & ribbon	Aluminium (Al)	7429-90-5		0.531	mg	1000000	5900
Encapsulation	Other inorganic materials	43.113	mg	supplier	mold compound	Silica, vitreous	60676-86-0		33.844	mg	785007	376044
				supplier	mold compound	epoxy resin	Proprietary		5.604	mg	129984	62267
				supplier	mold compound	phenol resin	9003-35-4		2.587	mg	60005	28744
				supplier	mold compound	metal hydroxide	Proprietary		0.862	mg	19994	9578
				supplier	mold compound	Carbon black	1333-86-4		0.216	mg	5010	2400
Connections coating	Solder	0.156	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.156	mg	1000000	1733